

Notice of References Cited

Application/Control No.

10/636,110

Applicant(s)/Patent Under
Reexamination
BALLANTINE ET AL.

Examiner

Tim Phan

Art Unit

3729

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,647,614 B1	11-2003	Ballantine et al.	29/610.1
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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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